Single 2-Input NAND Gate

The NL17SV00 is an ultra–high performance 2–Input NAND gate manufactured in 0.35 μm technology, with excellent performance down to 0.9 V. This device is ideal for extremely high speed and high–drive applications. Additionally, limitations of board space are no longer a constraint. The very small SOT–553 makes this device fit most tight designs and spaces.

Features

- Extremely High Speed: 1.0 ns (Typ) @ V_{CC} = 3.3 V
- Designed for 0.9 to 3.3 V Operation
- Overvoltage Tolerance (OVT)* Input Pins Permits Logic Translation
- Balanced ±24 mA Output Drive @ V_{CC} 3.3 V
- Near Zero Static Supply Current
- Ultra-Tiny SOT-553 5-Pin Package, only 1.6 x 1.6 x 0.6 mm
- All Devices in Package SOT-553 are Inherently Pb-Free**

Typical Applications

- Cellular
- Digital Camera
- PDA
- Digital Video

Industry Leadership

• Functionally Similar to NC7SV00 and SN74AUC1G00



Figure 1. Logic Symbol

FUNCTION TABLE

Inp	Output	
Α	Y	
L	L	Н
L	Н	Н
Н	L	Н
Н	Н	L

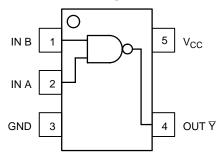


http://onsemi.com



UH = Specific Device Code
D = Date Code

PIN DIAGRAM



PIN ASSIGNMENT

PIN#	FUNCTION
1	IN B
2	IN A
3	GND
4	OUT \(\overline{Y} \)
5	V _{CC}

ORDERING INFORMATION

Device	Package	Shipping†
NL17SV00XV5T2	SOT-553 (Pb-Free)	4000 Tape & Reel (178 mm)

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}Overvoltage Tolerance (OVT) enables input pins to function outside (higher) of their operating voltages, with no damage to the devices or to signal integrity.

^{**}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS

Symbol	Rating		Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to + 4.6	V
VI	DC Input Voltage		-0.5 to + 4.6	V
Vo	DC Output Voltage		-0.5 to V _{CC} +0.5	V
I _{IK}	DC Input Diode Current	V _I < GND	±50	mA
l _{OK}	DC Output Diode Current	$V_O = GND$ $V_O = V_{CC}$	-50 +50	mA
Io	DC Output Sink Current		±50	mA
Icc	DC Supply Current per Supply Pin		±50	mA
I _{GND}	DC Ground Current per Ground Pin		±50	mA
T _{STG}	Storage Temperature Range		- 65 to +150	°C
TL	Lead Temperature, 1.0 mm from Case for 10 seconds		260	°C
T_J	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance (Note 1)		250	°C/W
P_{D}	Power Dissipation in Still Air at 85°C		250	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating Ox	ygen index: 28 to 34	UL 94 V-0 @ 0125 in	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

- Tested to EIA/JESD22-A114-A.
 Tested to EIA/JESD22-A115-A.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V _{CC}	Positive DC Supply Voltage		0.9	3.6	V
V _{IN}	Digital Input Voltage		0	3.6	V
V _{out}	Output Voltage		0	V _{CC}	V
I _{OH} /I _{OL}	Output Current	$\begin{array}{c} \text{V}_{\text{CC}} = 3.0 \text{ V to } 3.6 \text{ V} \\ \text{V}_{\text{CC}} = 2.3 \text{ V to } 2.7 \text{ V} \\ \text{V}_{\text{CC}} = 1.65 \text{ V to } 1.95 \text{ V} \\ \text{V}_{\text{CC}} = 1.4 \text{ V to } 1.6 \text{ V} \\ \text{V}_{\text{CC}} = 1.1 \text{ V to } 1.3 \text{ V} \\ \text{V}_{\text{CC}} = 0.9 \text{ V} \end{array}$		±24 ±18 ±6 ±4 ±2 ±0.1	mA
t _A	Operating Temperature Range. All Package Types		-40	+85	°C
t _r , t _f	Input Rise or Fall Time	$V_{CC} = 3.3V \pm 0.3 V$	0	10	nS/V

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

DC CHARACTERISTICS- Digital Section (Voltages Referenced to GND)

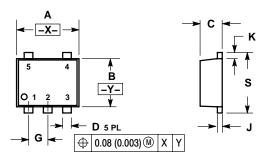
				T _A =	25°C	$T_A = -40$	to 85°C	
Symbol	Parameter	Condition	V _{CC}	Min	Max	Min	Max	Unit
V _{IH}	High Level		0.90	0.65 x V _{CC}		0.65 x V _{CC}		V
	Input Voltage		$1.10 \le = V_{CC} \le 1.30$	0.65 x V _{CC}		0.65 x V _{CC}		
			$1.40 \le V_{CC} \le 1.60$	0.65 x V _{CC}		0.65 x V _{CC}		
			$1.65 \le V_{CC} \le 1.95$	0.65 x V _{CC}		0.65 x V _{CC}		
			$2.30 \le V_{CC} \le 2.70$	1.6		1.6		
			$2.70 \le V_{CC} \le 3.60$	2.0		2.0		
V_{IL}	Low Level		0.90		0.35 x V _{CC}		$0.35 \times V_{CC}$	V
	Input Voltage		$1.10 \le V_{CC} \le 1.30$		0.35 x V _{CC}		0.35 x V _{CC}	
			$1.40 \le V_{CC} \le 1.60$		0.35 x V _{CC}		0.35 x V _{CC}	
			$1.65 \le V_{CC} \le 1.95$ $2.30 \le V_{CC} \le 2.70$		0.35 x V _{CC} 0.7		0.35 x V _{CC} 0.7	
			$2.30 \le V_{CC} \le 2.70$ $2.70 \le V_{CC} \le 3.60$		0.7		0.7	
V	Lligh Lovel	1 100 1		V 0.4	0.0	\/ 0.4	0.0	V
V_{OH}	High Level Output Voltage	$I_{OH} = -100 \mu A$	0.90 $1.10 \le V_{CC} \le 1.30$	$V_{CC} - 0.1$ $V_{CC} - 0.1$		$V_{CC} - 0.1$ $V_{CC} - 0.1$		V
	3.4		$1.40 \le V_{CC} \le 1.30$ $1.40 \le V_{CC} \le 1.60$	$V_{CC} = 0.1$ $V_{CC} = 0.2$		$V_{CC} = 0.1$ $V_{CC} = 0.2$		
			$1.65 \le V_{CC} \le 1.95$	V _{CC} - 0.2		V _{CC} - 0.2		
			$2.30 \le V_{CC} \le 2.70$	V _{CC} - 0.2		V _{CC} - 0.2		
			$2.70 \le V_{CC} \le 3.60$	V _{CC} - 0.2		V _{CC} - 0.2		
		I _{OH} = −2.0 mA	$1.10 \le V_{CC} \le 1.30$	0.75 x V _{CC}		0.75 x V _{CC}		
		$I_{OH} = -4.0 \text{ mA}$	$1.40 \le V_{CC} \le 1.60$	0.75 x V _{CC}		0.75 x V _{CC}		
		$I_{OH} = -6.0 \text{ mA}$	$1.65 \le V_{CC} \le 1.95$	1.25		1.25		
			$2.30 \le V_{CC} \le 2.70$	2.0		2.0		
		$I_{OH} = -12 \text{ mA}$	$2.30 \le V_{CC} \le 2.70$	1.8		1.8		
			$2.70 \le V_{CC} \le 3.60$	2.2		2.2		
		$I_{OH} = -18 \text{ mA}$	$2.30 \le V_{CC} \le 2.70$	1.7		1.7		
			$2.70 \le V_{CC} \le 3.60$	2.4		2.4		
		I _{OH} = -24 mA	$2.70 \le V_{CC} \le 3.60$	2.2		2.2		
V_{OL}	Low Level Output Voltage	$I_{OL} = 100 \mu A$	0.90		0.1		0.1	V
	Odipat Voltage		$1.10 \le V_{CC} \le 1.30$		0.1		0.1	
			$1.40 \le V_{CC} \le 1.60$ $1.65 \le V_{CC} \le 1.95$		0.2 0.2		0.2 0.2	
			$2.30 \le V_{CC} \le 1.33$		0.2		0.2	
			$2.70 \le V_{CC} \le 3.60$		0.2		0.2	
		I _{OL} = 2.0 mA	$1.10 \le V_{CC} \le 1.30$		0.25 x V _{CC}		0.25 x V _{CC}	
		I _{OL} = 4.0 mA	$1.40 \le V_{CC} \le 1.60$		0.25 x V _{CC}		0.25 x V _{CC}	
		I _{OL} = 6.0 mA	$1.65 \le V_{CC} \le 1.95$		0.3		0.3	
		I _{OL} = 12 mA	$2.30 \le V_{CC} \le 2.70$		0.4		0.4	
			$2.70 \le V_{CC} \le 3.60$		0.4		0.4	
		$I_{OL} = 18 \text{ mA}$	$2.30 \le V_{CC} \le 2.70$		0.6		0.6	
			$2.70 \le V_{CC} \le 3.60$		0.4		0.4	
		I _{OL} = 24 mA	$2.70 \le V_{CC} \le 3.60$		0.55		0.55	
I _{IN}	Input Leakage Current	0 = V _I = 3.6 V	0.90 to 3.60		±0.1		±0.9	μΑ
I _{OFF}	Power Off Leakage Current		0		1		5	μΑ
I _{CC}	Quiescent Supply Current	$V_I = V_{CC}$ or GND	0.90 to 3.60		0.9		5	μΑ

AC CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ nS}$)

		−40°C			25°C		85	°C	
Symbol	Parameter	Condition	V _{CC}	Min	Тур	Max	Min	Max	Unit
T _{PHL,}	Propagation Delay	$C_L = 15 \text{ pF}, R_L = 1.0 \text{ M}\Omega$	0.90		13				nS
T _{PLH}		C_L = 15 pF, R_L = 2.0 k Ω	$1.10 \le V_{CC} \le 1.30$ $1.40 \le V_{CC} \le 1.60$	3.0 1.0	6.0 3.2	9.9 6.0	1.0 1.0	14.6 7.2	nS
		C_L = 30 pF, R_L = 500 k Ω	$1.65 \le V_{CC} \le 1.95$ $2.30 \le V_{CC} \le 2.70$ $2.70 \le V_{CC} \le 3.60$	1.0 0.8 0.7	1.9 1.2 1.0	4.5 2.6 2.3	1.0 0.7 0.6	5.3 3.7 3.0	nS
C _{IN}	Input Capacitance		0		2.0				pF
C _{OUT}	Output Capacitance		0		4.5				pF
C _{PD}	Power Dissipation Capacitance	$V_I = 0 \text{ V or } V_{CC}$ F = 10 MHz	0.90 to 3.60		20				pF

PACKAGE DIMENSIONS

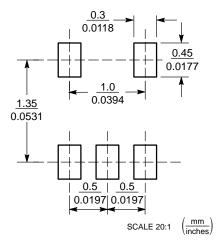
SOT-553 5-LEAD PACKAGE CASE 463B-01 ISSUE A



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETERS
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL OF BASE MATERIAL.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	1.50	1.70	0.059	0.067	
В	1.10	1.30	0.043	0.051	
O	0.50	0.60	0.020	0.024	
D	0.17	0.27	0.007	0.011	
G	0.50 BSC		0.020	BSC	
7	0.08	0.18	0.003	0.007	
K	0.10	0.30	0.004	0.012	
S	1.50	1.70	0.059	0.067	

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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